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Applicant : Asahi Kasei Corporation

Title : HEAT RESISTANT PHOTORESIST COMPOSITION

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2. What is Claimed is:

A heat resistant photoresist composition comprising 100 parts by weight of at least one polymer selected from polyamid acids, polyamide amines, polyamid acid amines, polymercaptop amide, polyhydroxyl amides, 10 polyhydrazides, polyoxathiahydrazides, and polyimides soluble in an organic polar solvent; 0.1 to 100 parts by weight of a compound having at least two ethylene series unsaturated double bonds in a molecule; and 0.01 to 20 parts by weight of at least one photopolymerization initiating agent selected from carbonyl compounds, peroxides, azo compounds, sulfur compounds, and 15 halides.